

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7069702

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MOKSHITH TEJASVI	12/13/2021
SARAVANAN GOVINDASAMY	12/11/2021
GIRISH MUDDENAHALLI HALESHPA	12/12/2021
RAVEEN JAGADEESAN	12/11/2021
RECEIVING PARTY DATA	
Name:	JUNIPER NETWORKS, INC.
Street Address:	1133 INNOVATION WAY
City:	SUNNYVALE
State/Country:	CALIFORNIA
Postal Code:	94089
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17548747
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	5714320800
Email:	docket@harrityllp.com
Correspondent Name:	HARRITY & HARRITY, LLP
Address Line 1:	11350 RANDOM HILLS ROAD
Address Line 2:	SUITE 600
Address Line 4:	FAIRFAX, VIRGINIA 22030
ATTORNEY DOCKET NUMBER:	0023-1114
NAME OF SUBMITTER:	SARA STESNEY
SIGNATURE:	/Sara Stesney/
DATE SIGNED:	12/13/2021
This document serves as an Oath/Declaration (37 CFR 1.63).	
Total Attachments: 2	

source=0023-1114_Assignment#page1.tif

source=0023-1114_Assignment#page2.tif

**DECLARATION AND ASSIGNMENT
FOR PATENT APPLICATION**

Declaration of Inventor

As a below named inventor, I hereby declare that:

- the above-identified application was made or authorized to be made by me;
- I believe that I am the original inventor or an original joint inventor of a claimed invention in the above-referenced application; and
- I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Inventor Assignment Acknowledgement

The terms of this patent rights Assignment are as follows:

WHEREAS, I, the below named inventor (hereinafter referred to as Assignor), have made an invention entitled:

CONTAINING ELECTROMAGNETIC INTERFERENCE RADIATION IN LIDLESS
SEMICONDUCTOR PACKAGES

for which an application is being filed herewith; or for which an application was filed for United States Letters Patent on December 13, 2021 under Serial No. 17/548,747; and

I hereby authorize Applicant's representative to fill in the preceding information relating to the filing date and/or serial number, as appropriate.

WHEREAS, Juniper Networks, Inc., a corporation of Delaware whose post office address is 1133 Innovation Way, Sunnyvale, CA 94089 (hereinafter referred to as Assignee), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application for United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that for good and valuable consideration the receipt of which from assignee is hereby acknowledged, I as assignor, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the assignee, its lawful successors and assigns, our entire right, title, and interest in and to this invention and this application, and including any previously or subsequently filed provisional applications, all divisions, continuations, and continuations-in-part thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such application, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and I hereby authorize and request the Commissioner of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent for this invention to assignee, its successors and assigns, in accordance with the terms of this Assignment;

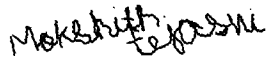
Docket No. 0023-1114
(Worldwide Rights)

AND, I HEREBY covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment;

AND, I HEREBY further covenant and agree that I will, without further consideration, communicate with assignee, its successors and assigns, any facts known to us respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the assignee, its successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hand.

Full legal name of Inventor: Mokshith TEJASVI

Signature:  Date: 12/13/2021

Full legal name of Inventor: Saravanan GOVINDASAMY

Signature:  Date: 12/11/2021

Full legal name of Inventor: Girish Muddenahalli HALESHAPPA

Signature:  Date: 12/12/2021

Full legal name of Inventor: Raveen JAGADEESAN

Signature:  Date: 12/11/2021